

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPB160N04S4L-H1	**Issued**	17. May 2021
MA#	MA005406724		
Package	PG-TO263-7-3	**Weight***	1527.13 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.138	0.34	0.34	3364	3364
leadframe	inorganic material	phosphorus	7723-14-0	0.241	0.02		158	
	non noble metal	iron	7439-89-6	0.803	0.05		526	
	non noble metal	copper	7440-50-8	801.714	52.49	52.56	524979	525663
wire	non noble metal	aluminium	7429-90-5	14.117	0.92	0.92	9244	9244
encapsulation	inorganic material	zincoxide	1314-13-2	5.822	0.38		3813	
	miscellaneous	miscellaneous	-	23.289	1.52		15250	
	plastics	epoxy resin	-	87.334	5.72		57189	
	inorganic material	silicondioxide	60676-86-0	465.784	30.50	38.12	305005	381257
leadfinish	non noble metal	tin	7440-31-5	12.317	0.81	0.81	8065	8065
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.269	0.02	0.02	176	177
solder	non noble metal	tin	7440-31-5	0.079	0.01		52	
	noble metal	silver	7440-22-4	0.099	0.01		65	
	non noble metal	lead	7439-92-1	3.776	0.25	0.27	2473	2590
heatspreader	inorganic material	phosphorus	7723-14-0	0.032			21	
	non noble metal	iron	7439-89-6	0.106	0.01		70	
	non noble metal	copper	7440-50-8	106.210	6.95	6.96	69549	69640
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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